


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	Method for Manufacturing Buried Insulating Layer Type Single Crystal Silicon Carbide Substrate and Manufacturing Device for the Same		
Application Type : regular, utility Attorney Docket Number : 040091			
Correspondence address: Customer Number: 23850 			
Priority Data: Doc.No: 2003-84056; Country -JP ; Date: 2003-03-26 us-priority-claimed			
Inventors Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: JP Given Name: Katsutoshi Family Name: IZUMI Residence: City of Residence: Osaka Country of Residence: JP Address-1 of Mailing Address: c/o Osaka Prefecture University, 1-1, Gakuen-cho, Address-2 of Mailing Address: Sakai, City of Mailing Address: Osaka State of Mailing Address: Postal Code of Mailing Address: 599-8531 Country of Mailing Address: JP Phone: Fax: E-mail: <u>Inventor 2:</u> Applicant Authority Type: Inventor Citizenship: JP			

Given Name: Motoi
Family Name: NAKAO
Residence:
City of Residence: Osaka
Country of Residence: JP
Address-1 of Mailing Address: c/o Osaka Prefecture University, 1-1, Gakuen-cho,
Address-2 of Mailing Address: Sakai,
City of Mailing Address: Osaka
State of Mailing Address:
Postal Code of Mailing Address: 599-8531
Country of Mailing Address: JP
Phone:
Fax:
E-mail:

Inventor 3:

Applicant Authority Type: Inventor
Citizenship: JP
Given Name: Yoshiaki
Family Name: OHBAYASHI
Residence:
City of Residence: Nara
Country of Residence: JP
Address-1 of Mailing Address: c/o Hosiden Corporation, 4-33, Kitakyuhoji
Address-2 of Mailing Address: 1-chome, Yao-shi,
City of Mailing Address: Osaka
State of Mailing Address:
Postal Code of Mailing Address: 581-0071
Country of Mailing Address: JP
Phone:
Fax:
E-mail:

Inventor 4:

Applicant Authority Type: Inventor
Citizenship: JP
Given Name: Keiji
Family Name: MINE
Residence:
City of Residence: Osaka
Country of Residence: JP
Address-1 of Mailing Address: c/o Hosiden Corporation, 4-33, Kitakyuhoji

Address-2 of Mailing Address: 1-chome, Yao-shi,
City of Mailing Address: Osaka
State of Mailing Address:
Postal Code of Mailing Address: 581-0071
Country of Mailing Address: JP
Phone:
Fax:
E-mail:

Inventor 5:

Applicant Authority Type: Inventor
Citizenship: JP
Given Name: Seisaku
Family Name: HIRAI
Residence:
City of Residence: Osaka
Country of Residence: JP
Address-1 of Mailing Address: c/o Hosiden Corporation, 4-33, Kitakyuhoji
Address-2 of Mailing Address: 1-chome, Yao-shi,
City of Mailing Address: Osaka
State of Mailing Address:
Postal Code of Mailing Address: 581-0071
Country of Mailing Address: JP
Phone:
Fax:
E-mail:

Inventor 6:

Applicant Authority Type: Inventor
Citizenship: JP
Given Name: Fumihiko
Family Name: JOBE
Residence:
City of Residence: Osaka
Country of Residence: JP
Address-1 of Mailing Address: c/o Hosiden Corporation, 4-33, Kitakyuhoji
Address-2 of Mailing Address: 1-chome, Yao-shi,
City of Mailing Address: Osaka
State of Mailing Address:
Postal Code of Mailing Address: 581-0071
Country of Mailing Address: JP
Phone:

Fax:

E-mail:

Inventor 7:

Applicant Authority Type: Inventor
Citizenship: JP
Given Name: Tomoyuki
Family Name: TANAKA
Residence:
City of Residence: Osaka
Country of Residence: JP
Address-1 of Mailing Address: c/o Hosiden Corporation, 4-33, Kitakyuhoji
Address-2 of Mailing Address: 1-chome, Yao-shi,
City of Mailing Address: Osaka
State of Mailing Address:
Postal Code of Mailing Address: 581-0071
Country of Mailing Address: JP
Phone:
Fax:
E-mail:

Attorney Information:

practitioner(s) at Customer Number:

23850



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Assignee 1:

Organization Name: Osaka Prefecture,
Address-1 of Mailing Address: 2-1-22, Otemae,
Address-2 of Mailing Address: Chuo-ku, Osaka-shi,
City of Mailing Address: Osaka,
State of Mailing Address:
Postal Code of Mailing Address: 540-8570
Country of Mailing Address: JP
Phone:
Fax:
E-mail:

Assignee 2:

Organization Name: Hosiden Corporation
Address-1 of Mailing Address: 4-33, Kitakyuhoji 1-chome,

Address-2 of Mailing Address:	Yao-shi,
City of Mailing Address:	Osaka,
State of Mailing Address:	
Postal Code of Mailing Address:	581-0071
Country of Mailing Address:	JP
Phone:	
Fax:	
E-mail:	